Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.060”**

**.060”**

**ANODE**

**.053 x .053”**

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size = .053” X .053”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .060” X .060” DATE: 11/10/21**

**MFG: ON SEMI / MOTOROLA THICKNESS .007” P/N: 1N5821**

**DG 10.1.2**

#### Rev B, 7/1